COM'L: -7/10/12/15/20, Q-12/15/20 IND: -12/14/18/24

MACH210A-7/10/12 MACH210-12/15/20 MACH210AQ-12/15/20

Advanced Micro Devices

High-Density EE CMOS Programmable Logic

DISTINCTIVE CHARACTERISTICS

- 44 Pins
- 64 Macrocells
- 7.5 ns t_{PD} Commercial
 12 ns t_{PD} Industrial
- 133 MHz fcnt
- 38 Inputs; 210A Inputs have built-in pull-up resistors
- Peripheral Component Interconnect (PCI) compliant
- 32 Outputs
- 64 Flip-flops; 2 clock choices
- 4 "PAL22V16" blocks with buried macrocells
- Pin-compatible with MACH110, MACH111, MACH211, and MACH215

GENERAL DESCRIPTION

The MACH210 is a member of AMD's high-performance EE CMOS MACH 2 device family. This device has approximately six times the logic macrocell capability of the popular PAL22V10 without loss of speed.

The MACH210 consists of four PAL blocks interconnected by a programmable switch matrix. The four PAL blocks are essentially "PAL22V16" structures complete with product-term arrays and programmable macrocells, including additional buried macrocells. The switch matrix connects the PAL blocks to each other and to all input pins, providing a high degree of connectivity between the fully-connected PAL blocks. This allows designs to be placed and routed efficiently.

The MACH210 has two kinds of macrocell: output and buried. The MACH210 output macrocell provides regis-

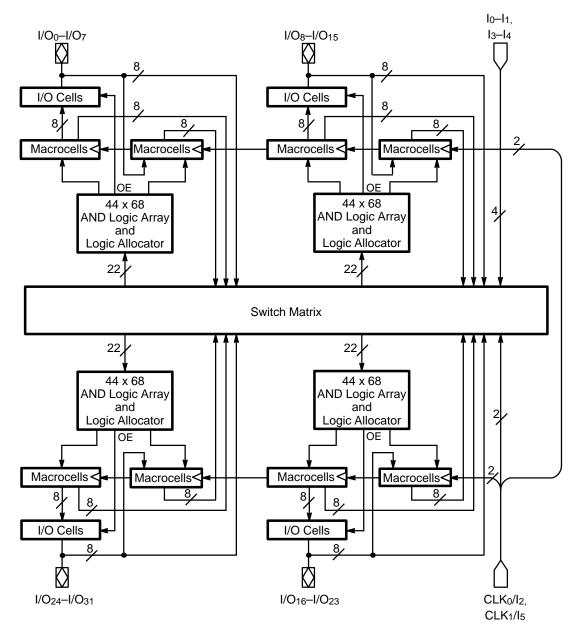
tered, latched, or combinatorial outputs with programmable polarity. If a registered configuration is chosen, the register can be configured as D-type or T-type to help reduce the number of product terms. The register type decision can be made by the designer or by the software. All output macrocells can be connected to an I/O cell. If a buried macrocell is desired, the internal feedback path from the macrocell can be used, which frees up the I/O pin for use as an input.

The MACH210 has dedicated buried macrocells which, in addition to the capabilities of the output macrocell, also provide input registers or latches for use in synchronizing signals and reducing setup time requirements.

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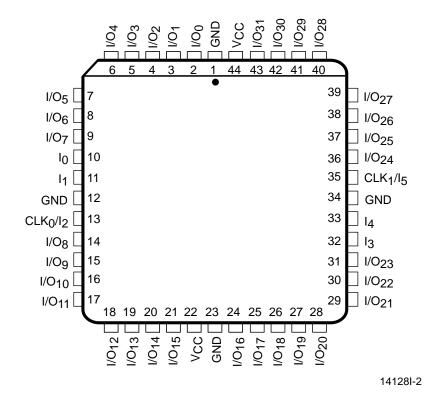
BLOCK DIAGRAM



141281-1

CONNECTION DIAGRAM Top View

PLCC

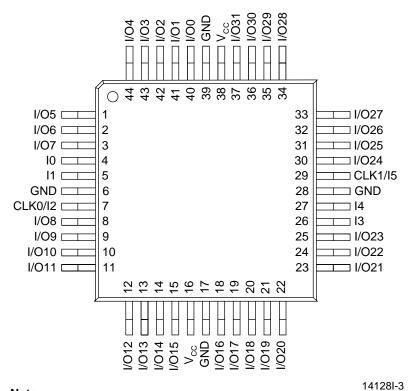


Note: Pin-compatible with MACH110, MACH111, MACH211, and MACH215.



CONNECTION DIAGRAM Top View

TQFP



Note: Pin-compatible with MACH111 and MACH211.

PIN DESIGNATIONS

CLK/I = Clock or Input

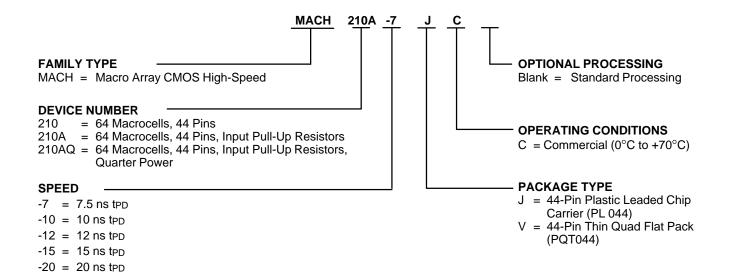
GND = Ground I = Input

I/O = Input/Output Vcc = Supply Voltage



ORDERING INFORMATION Commercial Products

AMD programmable logic products for commercial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



Valid Combinations				
MACH210A-7	10			
MACH210A-10	JC, VC			
MACH210A-12				
MACH210-12				
MACH210-15				
MACH210-20	JC			
MACH210AQ-12	30			
MACH210AQ-15				
MACH210AQ-20				

Valid Combinations

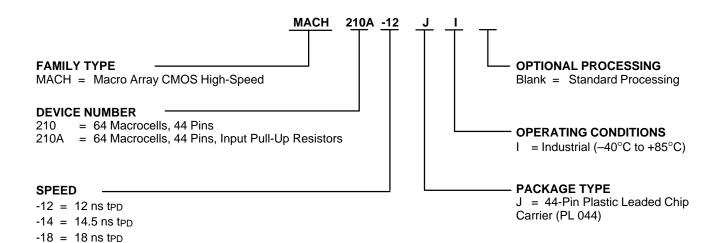
The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.



-24 = 24 ns tpd

ORDERING INFORMATION Industrial Products

AMD programmable logic products for industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



Valid Combinations					
MACH210A-12					
MACH210A-14					
MACH210-14	JI				
MACH210-18					
MACH210-24					

Valid Combinations

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations.



FUNCTIONAL DESCRIPTION

The MACH210 consists of four PAL blocks connected by a switch matrix. There are 32 I/O pins and 4 dedicated input pins feeding the switch matrix. These signals are distributed to the four PAL blocks for efficient design implementation. There are two clock pins that can also be used as dedicated inputs.

The MACH210A inputs and I/O pins have built-in pull-up resistors. While it is always a good design practice to tie unused pins high, the 210A pull-up resistors provide design security and stability in the event that unused pins are left disconnected.

The PAL Blocks

Each PAL block in the MACH210 (Figure 1) contains a 64-product-term logic array, a logic allocator, 8 output macrocells, 8 buried macrocells, and 8 I/O cells. The switch matrix feeds each PAL block with 22 inputs. This makes the PAL block look effectively like an independent "PAL22V16" with 8 buried macrocells.

In addition to the logic product terms, two output enable product terms, an asynchronous reset product term, and an asynchronous preset product term are provided. One of the two output enable product terms can be chosen within each I/O cell in the PAL block. All flip-flops within the PAL block are initialized together.

The Switch Matrix

The MACH210 switch matrix is fed by the inputs and feedback signals from the PAL blocks. Each PAL block provides 16 internal feedback signals and 8 I/O feedback signals. The switch matrix distributes these signals back to the PAL blocks in an efficient manner that also provides for high performance. The design software automatically configures the switch matrix when fitting a design into the device.

The Product-term Array

The MACH210 product-term array consists of 64 product terms for logic use, and 4 special-purpose product terms. Two of the special-purpose product terms provide programmable output enable; one provides asynchronous reset, and one provides asynchronous preset.

The Logic Allocator

The logic allocator in the MACH210 takes the 64 logic product terms and allocates them to the 16 macrocells as needed. Each macrocell can be driven by up to 16 product terms. The design software automatically configures the logic allocator when fitting the design into the device.

Table 1 illustrates which product term clusters are available to each macrocell within a PAL block. Refer to Figure 1 for cluster and macrocell numbers.

Table 1. Logic Allocation

Mac	rocell	Available
Output	Buried	Clusters
Mo	M ₁	C ₀ , C ₁ , C ₂ C ₀ , C ₁ , C ₂ , C ₃
M ₂	M ₃	C ₁ , C ₂ , C ₃ , C ₄ C ₂ , C ₃ , C ₄ , C ₅
M ₄	M ₅	C ₃ , C ₄ , C ₅ , C ₆ C ₄ , C ₅ , C ₆ , C ₇
M ₆	M ₇	C ₅ , C ₆ , C ₇ , C ₈ C ₆ , C ₇ , C ₈ , C ₉
M ₈	M ₉	C ₇ , C ₈ , C ₉ , C ₁₀ C ₈ , C ₉ , C ₁₀ , C ₁₁
M 10	M ₁₁	C ₉ , C ₁₀ , C ₁₁ , C ₁₂ C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₁₂	M ₁₃	C11, C12, C13, C14 C12, C13, C14, C15
M ₁₄	M ₁₅	C13, C14, C15 C14, C15

The Macrocell

The MACH210 has two types of macrocell: output and buried. The output macrocells can be configured as either registered, latched, or combinatorial, with programmable polarity. The macrocell provides internal feedback whether configured with or without the flipflop. The registers can be configured as D-type or T-type, allowing for product-term optimization.

The flip-flops can individually select one of two clock/ gate pins, which are also available as data inputs. The registers are clocked on the LOW-to-HIGH transition of the clock signal. The latch holds its data when the gate input is HIGH, and is transparent when the gate input is LOW. The flip-flops can also be asynchronously initialized with the common asynchronous reset and preset product terms.

The buried macrocells are the same as the output macrocells if they are used for generating logic. In that case, the only thing that distinguishes them from the output macrocells is the fact that there is no I/O cell connection, and the signal is only used internally. The buried macrocell can also be configured as an input register or latch.



The I/O Cell

The I/O cell in the MACH210 consists of a three-state output buffer. The three-state buffer can be configured in one of three ways: always enabled, always disabled, or controlled by a product term. If product term control is chosen, one of two product terms may be used to provide the control. The two product terms that are available are common to all I/O cells in a PAL block.

These choices make it possible to use the macrocell as an output, an input, a bidirectional pin, or a three-state output for use in driving a bus.

PCI Compliance

The MACH210A-7/10 is fully compliant with the *PCI Local Bus Specification* published by the PCI Special Interest Group. The MACH210A-7/10's predictable timing ensures compliance with the PCI AC specifications independent of the design. On the other hand, in CPLD and FPGA architectures without predictable timing, PCI compliance is dependent upon routing and product term distribution.

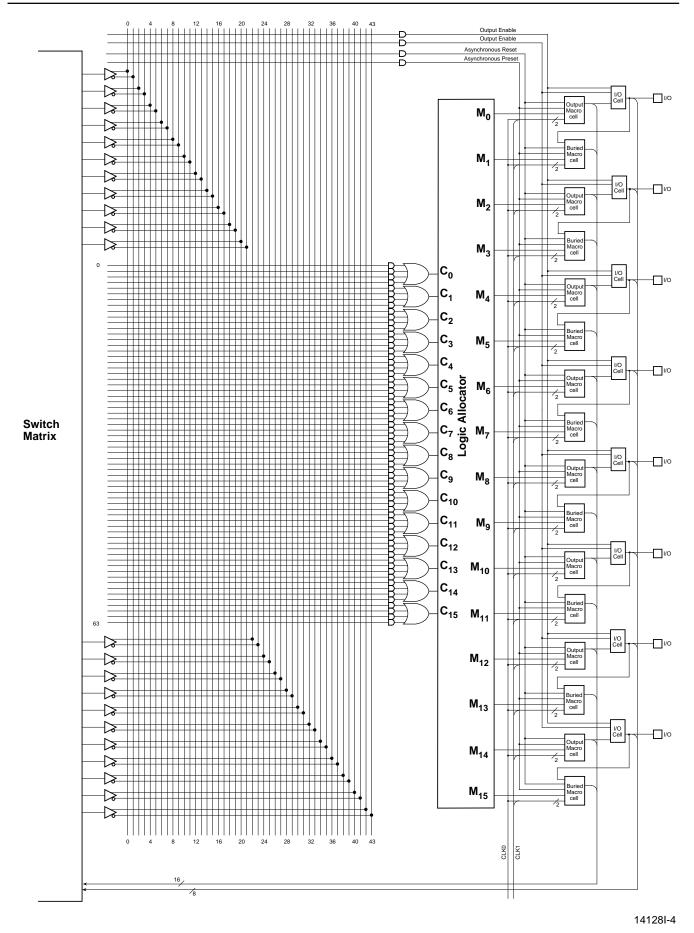


Figure 1. MACH210 PAL Block



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage -0.5 V to V_{CC} + 0.5 V
DC Output or
I/O Pin Voltage -0.5 V to V_{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current
$(T_A = 0^{\circ}C \text{ to } +70^{\circ}C) \dots 200 \text{ mA}$

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air	0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2 mA, VCC = Min VIN = VIH or VIL	2.4			V
Vol	Output LOW Voltage	I _{OL} = 16 mA, V _{CC} = Min V _{IN} = V _{IH} or V _{IL}			0.5	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
Іін	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
lı∟	Input LOW Leakage Current	Vin = 0 V, Vcc = Max (Note 2)			-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			10	μΑ
l _{OZL}	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = Vih or Vil (Note 2)			-100	μΑ
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current	VIN = 0 V, Outputs Open (Iout = 0 mA) VCC = 5.0 V, f = 25 MHz, T _A = 25°C (Note 4)		130		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. This parameter is measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and capable of being loaded, enabled, and reset.

Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
CIN	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges

Parameter				-7	,]
Symbol	Parameter Description			Min	Max	Unit
t _{PD}	Input, I/O, or Feedback to Combinatorial Output			7.5	ns	
ts	Setup Time	e from Input, I/O or Feedback to Clock	D-Type	5.5		ns
		Т-Туре		6.5		ns
tн	Register D	ata Hold Time		0		ns
tco	Clock to O	utput			5	ns
tw∟	Clock Widt	h	LOW	3		ns
twH			HIGH	3		ns
		Cutawa I Candle adv	D-Type	100		MHz
	Maximum	External Feedback	T-Type	91		MHz
fmax	Frequency		D-Type	133		MHz
		Internal Feedback (fcnt)	T-Type	125		MHz
		No Feedback	·	166.7		MHz
tsL	Setup Time	e from Input, I/O, or Feedback to Gate		5.5		ns
tHL	Latch Data Hold Time					ns
tgo	Gate to Output			6	ns	
tgwL	Gate Width LOW		3		ns	
tpDL	Input, I/O, or Feedback to Output Through Transparent Input or Output Latch			9.5	ns	
tsır	Input Regis	ster Setup Time		2		ns
thir	Input Regis	ster Hold Time		2		ns
tico	Input Regis	ster Clock to Combinatorial Output			11	ns
tics	Input Regis	ster Clock to Output Register Setup	D-Type	9		ns
			T-Type	10		ns
twicl	Input Regis	ster Clock Width	LOW	3		ns
twich			HIGH	3		ns
fmaxir	Maximum	Input Register Frequency	•	166.7		MHz
tsıL	Input Latch	n Setup Time		2		ns
tHIL	Input Latch	n Hold Time		2		ns
tigo	Input Latch	n Gate to Combinatorial Output			12	ns
tigoL	Input Latch	n Gate to Output Through Transparent Output Latch	1		14	ns
tsll		e from Input, I/O, or Feedback Through nt Input Latch to Output Latch Gate		7.5		ns



SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (continued)

Parameter		-7		
Symbol	Parameter Description	Min	Max	Unit
tigs	Input Latch Gate to Output Latch Setup	10		ns
twigL	Input Latch Gate Width LOW	3		ns
tPDLL	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		11.5	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		12	ns
tarw	Asynchronous Reset Width	8		ns
tarr	Asynchronous Reset Recovery Time	8		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		12	ns
tapw	Asynchronous Preset Width	8		ns
tapr	Asynchronous Preset Recovery Time	8		ns
tEA	Input, I/O, or Feedback to Output Enable		7.5	ns
t _{ER}	Input, I/O, or Feedback to Output Disable		7.5	ns

^{1.} These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air 0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75 V to +5.25 \

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
V _{ОН}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			٧
V_{OL}	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I⊫	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μΑ
l _{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μА
I _{sc}	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max (Note 3)}$	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5V, T _A = 25°C, f = 25 MHz (Note 4)		135		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.



Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter						-	0	-12		
Symbol	Parameter I	Description				Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	Feedback to Combin	natorial C	Output			10		12	ns
,	Setup Time	from Input, I/O,			D-Type	6.5		7		ns
ts	or Feedback	or Feedback to Clock T-Type				7.5		8		ns
t _H	Register Dat	ta Hold Time				0		0		ns
tco	Clock to Out	tput (Note 3)					6		8	ns
tw∟	Clock	Clock		LOW	5		6		ns	
t _{WH}	Width	/idth		HIGH	5		6		ns	
			l		D-Type	80		66.7		MHz
	Maximum	External Feedback	1/(ts + t	tco)	T-Type	74		62.5		MHz
f _{MAX}	Frequency		•		D-Type	100		83.3		MHz
	(Note 1)	Internal Feedback (fcnt)		T-Type	91		76.9		MHz
		No Feedback	•	100		83.3		MHz		
tsL	Setup Time	Setup Time from Input, I/O, or Feedback to Gate				6.5		7		ns
t _{HL}	Latch Data Hold Time				0		0		ns	
t _{GO}	Gate to Outp	out (Note 3)					7		10	ns
t _{GWL}	Gate Width I	,				5		6		ns
t _{PDL}	Input, I/O, or	Feedback to Output	Through	1						
		Input or Output Latcl					12		14	ns
tsır	Input Regist	er Setup Time				2		2		ns
t _{HIR}	Input Regist	er Hold Time				2		2		ns
t _{ICO}	Input Regist	er Clock to Combinat	torial Out	put			13		15	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Se	etup	D-Type	10		12		ns
					T-Type	11		13		ns
twicl	Input Regist	er			LOW	5		6		ns
twich	Clock Width				HIGH	5		6		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(1	twicL + twi	сн)	100		83.3		MHz
tsıL	Input Latch	Setup Time				2		2		ns
t _{HIL}	Input Latch I	Hold Time				2		2		ns
tigo	Input Latch	Gate to Combinatorial Output					14		17	ns
tigoL	Input Latch (Output Latch	Gate to Output Throu า	gh Trans	parent			16		19	ns
tsll		from Input, I/O, or Fe Input Latch to Outpu				8.5		9		ns
t _{iGS}	Input Latch	Gate to Output Latch	Setup			11	1	13		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	0	-12		
Symbol	Parameter Description	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	5		6		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		14		16	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		25		16	ns
tarw	Asynchronous Reset Width (Note 1)	10		12		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	10		8		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		15		16	ns
tapw	Asynchronous Preset Width (Note 1)	10		12		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	10		8		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		10		12	ns
ter	Input, I/O, or Feedback to Output Disable (Note 3)		10		12	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to V _{CC} + 0.5 V
DC Output or
I/O Pin Voltage -0.5 V to V_{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0^{\circ}C$ to $+70^{\circ}C$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Temperature (T_A) Operating in Free Air	–40°C to +85°C
Supply Voltage (V _{CC}) with Respect to Ground	+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
V _{ОН}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			>
V _{OL}	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	٧
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	٧
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μΑ
l _{оzн}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μΑ
I _{sc}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5V, T _A = 25°C, f = 25 MHz (Note 4)		135		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Parameter Symbol	Parameter Description	Test Conditio	Test Conditions		
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter						-1	2	-1-	4	
Symbol	Parameter I	Description				Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combi	natorial Ou	tput			12		14.5	ns
		from Input, I/O,			D-Type	8		8.5		ns
t s	or Feedback to Clock T-Type				9		10		ns	
t _H	Register Da	ister Data Hold Time				0		0		ns
tco	Clock to Out	tput (Note 3)					7.5		10	ns
tw∟	Clock	lock		LOW	6		7.5		ns	
t _{WH}	Width	/idth		HIGH	6		7.5		ns	
					D-Type	64		53		MHz
	Maximum	External Feedback	1/(ts + tcc	o)	T-Type	59		50		MHz
f _{MAX}	f _{MAX} Frequency		•		D-Type	80		61.5		MHz
	(Note 1)	Internal Feedback (fcnt)		T-Type	72.5		57		MHz
		No Feedback	1/(ts + t _H)		80		66.5		MHz	
tsL	Setup Time from Input, I/O, or Feedback to Gate				8		8.5		ns	
t _{HL}	Latch Data Hold Time				0		0		ns	
tgo	Gate to Out						8.5		12	ns
t _{GWL}		Gate Width LOW				6		7.5		ns
t _{PDL}		nput, I/O, or Feedback to Output Through						- 110		- 110
-1 52		Input or Output Latel					14.5		17	ns
tsir	Input Regist	er Setup Time				2.5		2.5		ns
t _{HIR}	Input Regist	er Hold Time				3		3		ns
t _{ICO}	Input Regist	er Clock to Combinat	orial Outpu	ıt			16		18	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Setu	qı	D-Type	12		14.5		ns
					T-Type	13		16		ns
twicl	Input Regist	er			LOW	6		7.5		ns
twich	Clock Width				HIGH	6		7.5		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(twi	cL + twi	сн)	80		66.5		MHz
tsıL	Input Latch	Setup Time				2.5		2.5		ns
tHIL	Input Latch	Hold Time				3		3		ns
tigo	Input Latch	out Latch Gate to Combinatorial Output					17		20.5	ns
tigoL	Input Latch Output Latch	Gate to Output Throu	gh Transpa	arent			19.5		23	ns
tsll	Setup Time	from Input, I/O, or Fe Input Latch to Outpu				10.5		11		ns
t _{IGS}	·	Gate to Output Latch		•		13.5		16		ns
-,50										•



SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	2	-14		
Symbol	Parameter Description	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		7.5		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		17		19.5	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		19.5		19.5	ns
tarw	Asynchronous Reset Width (Note 1)	12		14.5		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	12		10		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		18		19.5	ns
t _{APW}	Asynchronous Preset Width (Note 1)	12		14.5		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	12		10		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		12		14.5	ns
ter	Input, I/O, or Feedback to Output Disable (Note 3)		12	·	14.5	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.



Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air 0°	C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75 V	′ to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
V _{он}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}		2.4		V
V _{OL}	Output LOW Voltage	$I_{OL} = 16$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			8.0	V
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-10	μΑ
l _{оzн}	Off-State Output Leakage Current HIGH	$V_{\text{OUT}} = 5.25 \text{ V}, V_{\text{CC}} = \text{Max}$ $V_{\text{IN}} = V_{\text{IH}} \text{ or } V_{\text{IL}} \text{ (Note 2)}$			10	μА
l _{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-10	μА
I _{sc}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)		-30	-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5V, T _A = 25°C, f = 25 MHz (Note 4)		120		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.



Parameter Symbol	Parameter Description	Test Condition	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter						-1:	2	-1		-20	0	
Symbol	Parameter I	Description				Min	Max	Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	Feedback to Combi	natori	ial Output			12		15		20	ns
	Setup Time	from Input, I/O,			D-type	7		10		13		ns
ts	or Feedback	to Clock			T-type	8		11		14		ns
t⊢	Register Dat	ta Hold Time			•	0		0		0		ns
tco	Clock to Output (Note 3)				8		10		12	ns		
tw∟	Clock				6		6		8		ns	
twн	Width HIGH			6		6		8		ns		
	External Feedback 1/(ts + tco)	D-type	66.7		50		40		MHz			
Maximun	Maximum	External Feedback	1/(ts	s + tco)	T-type	62.5		47.6		38.5		MHz
f _{MAX}	Frequency		•		D-type	83.3		66.6		50		MHz
	(Note 1)	Internal Feedback (fcnt)		T-type	76.9		62.5		47.6		MHz
		No Feedback	lo Feedback 1/(t _{WL} + t _{WH})			83.3		83.3		62.5		MHz
t _{SL}	Setup Time from Input, I/O, or Feedback to Gate			7		10		13		ns		
tHL	Latch Data Hold Time			0		0		0		ns		
tgo		Gate to Output (Note 3)				10		11		12	ns	
tgwL	Gate Width	, ,				6		6		8		ns
tpDL	Input, I/O, or	Feedback to Output	Thro	ough								
		Input or Output Latel					14		17		22	ns
tsir	Input Regist	er Setup Time				2		2		2		ns
t _{HIR}	Input Regist	er Hold Time				2		2.5		3		ns
tico	Input Regist	er Clock to Combinat	torial	Output			15		18		23	ns
tics	Input Regist	er Clock to Output Re	egiste	er Setup	D-type	12		15		20		ns
					T-type	13		16		21		ns
twicl	Input Regist	er			LOW	6		6		8		ns
twich	Clock Width				HIGH	6		6		8		ns
fmaxir	Maximum In	put Register Frequer	псу	1/(twick + twick	сн)	83.3		83.3		62.5		MHz
t _{SIL}	Input Latch	Setup Time				2		2		2		ns
thiL	Input Latch I	Hold Time				2		2.5		3		ns
tigo	Input Latch (Gate to Combinatoria	ıl Out	put			17		20		25	ns
tigoL	Input Latch Gate to Output Through Transparent Output Latch				19		22		27	ns		
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu				9		12		15		ns
tigs	•	Gate to Output Latch				13		16		21		ns
	Input Later Gate to Gatput Later Getap											

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	2	-1	5	-20		
Symbol	Parameter Description	Min	Max	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		6		8		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		16		19		24	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output 16 20 2		25	ns				
t _{ARW}	Asynchronous Reset Width (Note 1)	12		15		20		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	8		10		15		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		16		20		25	ns
tapw	Asynchronous Preset Width (Note 1)	12		15		20		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	8		10		15		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		12		15		20	ns
ter	Input, I/O, or Feedback to Output Disable (Note 3)		12		15		20	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.



Storage Temperature65°C to +150°C
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage –0.5 V to V _{CC} + 0.5 V
DC Output or I/O
Pin Voltage –0.5 V to Vcc+ 0.5 V
Static Discharge Voltage 2001 V
Latchup Current $ (T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}) \ \dots \ 200 \ \text{mA} $

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Ambient Temperature (T_A)
Operating in Free Air -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
Vol	Output LOW Voltage	I _{OL} = 16 mA, V _{CC} = Min V _{IN} = V _{IH} or V _{IL}			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
I _{IL}	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-10	μΑ
lozн	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)			10	μА
l _{OZL}	Off-State Output Leakage Current LOW	V _{OUT} = 0 V, V _{CC} = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			-10	μΑ
I _{SC}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		120		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)

Parameter					-14 -18 -24						
Symbol	Parameter I	Description			Min	Max	Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combi	natorial Output			14.5		18		24	ns
4-		from Input, I/O,		D-type	8.5		12		16		ns
ts	or Feedback	to Clock		T-type	10		13.5		17		ns
t _H	Register Dat	ta Hold Time			0		0		0		ns
tco	Clock to Out	tput (Note 3)				10		12		14.5	ns
t _{WL}	Clock			LOW	7.5		7.5		10		ns
twH	Width	T	1	HIGH	7.5		7.5		10		ns
		External Feedback	1/(t _S + t _{CO})	D-type	53		40		32		MHz
	Maximum		17(10 1 100)	T-type	50		38		30.5		MHz
f_{MAX}	Frequency	latamal Faadhaala (£ \	D-type	61.5		53		38		MHz
	(Note 1)	Internal Feedback (CNT)	T-type	57		44		34.5		MHz
		No Feedback	1/(t _{WL} + t _{WH})		66.5		66.5		50		MHz
t _{SL}	Setup Time from Input, I/O, or Feedback to Gate				8.5		12		16		ns
t⊢∟	Latch Data Hold Time			0		0		0		ns	
t _{GO}	Gate to Output (Note 3)				12		13.5		14.5	ns	
t _{GWL}	Gate Width LOW			7.5		7.5		10		ns	
t _{PDL}	Input, I/O, or Feedback to Output Through Transparent Input or Output Latch				17		20.5		26.5	ns	
t _{SIR}	Input Register Setup Time		2.5		2.5		2.5		ns		
t _{HIR}	Input Register Hold Time		3		3.5		4		ns		
t _{ICO}	Input Regist	er Clock to Combinat	orial Output			18		22		28	ns
tics	Input Regist	er Clock to Output Re	egister Setup	D-type	14.5		18		24		ns
				T-type	16		19.5		25.5		ns
twicL	Input Regist	er		LOW	7.5		7.5		10		ns
twich	Clock Width			HIGH	7.5		7.5		10		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(t _{WICL} + t	wich)	66.5		66.5		50		MHz
t _{SIL}	Input Latch	Setup Time	•		2.5		2.5		2.5		ns
t _{HIL}	Input Latch I	Hold Time			3		3.5		4		ns
tigo	Input Latch (Gate to Combinatoria	l Output			20.5		24		30	ns
t _{IGOL}	Input Latch (Output Latch	Gate to Output Throu า	gh Transparent			23		26.5		32.5	ns
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu		1	11		14.5		18		ns
t _{IGS}	Input Latch Gate to Output Latch Setup			16		19.5		25.5		ns	
twigL	Input Latch (Gate Width LOW			7.5		7.5		10		ns
t _{PDLL}		r Feedback to Output utput Latches	Through Transp	parent		19.5		23		29	ns



SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2) (continued)

Parameter		-1	-14		-18		-24	
Symbol	Parameter Description	Min	Max	Min	Max	Min	Max	Unit
t _{AR}	Asynchronous Reset to Registered or Latched Output		19.5		24		30	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	14.5 18		24		ns		
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	10		12		18		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		19.5		24		30	ns
t _{APW}	Asynchronous Preset Width (Note 1)	14.5		18		24		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	10		12		18		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		14.5		18		24	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		14.5		18		24	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.



Storage Temperature -65° C to $+150^{\circ}$ C Ambient Temperature with Power Applied -55° C to $+125^{\circ}$ C Supply Voltage with Respect to Ground -0.5 V to +7.0 V DC Input Voltage -0.5 V to +7.0 V DC Output or I/O Pin Voltage -0.5 V to +7.0 V Static Discharge Voltage +7.0 V Latchup Current (+7.0 C to +7.0 C) +7.0 V Latchup Current (+7.0 C to +7.0 C) +7.0 C mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air 0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75 V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}, V_{CC} = Min$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
Іін	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I₁∟	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-100	μΑ
l _{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μΑ
Isc	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max (Note 3)}$	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.



Parameter Symbol	Parameter Description	Test Condition	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter				-12	2	
Symbol	Parameter	Description		Min	Max	Unit
t _{PD}	Input, I/O, or Feedback to Combinatorial Output				12	ns
	Setup Time	from Input, I/O,	D-type	12		ns
ts l	or Feedback to Clock T-type		T-type	13		ns
tн	Register Da	ta Hold Time	•	0		ns
tco	Clock to Ou	tput			6	ns
tw∟	Clock		LOW	6		ns
twн	Width		HIGH	6		ns
			D-type	55.6		MHz
	Maximum	External Feedback	T-type	52.6		MHz
f_{MAX}	Frequency		D-type	83.3		MHz
	(Note 1)	Internal Feedback (fcnt)	T-type	76.9		MHz
		No Feedback	'	83.3		MHz
t _{SL}	Setup Time	from Input, I/O, or Feedback to Gate		12		ns
t _{HL}	Latch Data I	Hold Time		0		ns
tgo	Gate to Out	put			7	ns
t _{GWL}	Gate Width	LOW		6		ns
t _{PDL}	Input, I/O, o	r Feedback to Output Through				
		t Input or Output Latch			14	ns
tsir	Input Regist	er Setup Time		2		ns
t _{HIR}	Input Regist	er Hold Time		2.5		ns
tico	Input Regist	er Clock to Combinatorial Output			17	ns
tics	Input Regist	er Clock to Output Register Setup	D-type	15		ns
			T-type	16		ns
twicl	Input Regist	er	LOW	6		ns
twich	Clock Width		HIGH	6		ns
f _{MAXIR}	Maximum In	put Register Frequency		83.3		MHz
t _{SIL}	Input Latch Setup Time			2		ns
t _{HIL}	Input Latch Hold Time			2.5		ns
t _{IGO}	Input Latch	Gate to Combinatorial Output			19	ns
tigol		Gate to Output Through Transparent				
	Output Latcl				20	ns
tsll		from Input, I/O, or Feedback Through				
		t Input Latch to Output Latch Gate		13		ns
tıgs	Input Latch	Gate to Output Latch Setup		16		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	-12	
Symbol	Parameter Description	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		18	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		24	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	19		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	19		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		24	ns
t _{APW}	Asynchronous Preset Width (Note 1)	19		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	19		ns
t _{EA}	Input, I/O, or Feedback to Output Enable		12	ns
t _{ER}	Input, I/O, or Feedback to Output Disable		12	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.



Storage Temperature –65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or
I/O Pin Voltage $\dots -0.5 \text{ V}$ to $V_{CC} + 0.5 \text{ V}$
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0^{\circ}C$ to $+70^{\circ}C$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air	0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
V _{он}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			>
V_{OL}	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
Iн	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
I⊩	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μΑ
lоzн	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
l _{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μΑ
I _{sc}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	$V_{CC} = 5V$, $T_A = 25^{\circ}C$, $f = 25$ MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Parameter Symbol	Parameter Description	Test Condition	Тур	Unit	
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter					-1:	5	-2	0	
Symbol	Parameter Description				Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or Feedback to Combinatorial Output (Note 3)					15		20	ns
		from Input, I/O,		D-type	13		17		ns
ts	or Feedback	to Clock		T-type	14		18		ns
t _H	Register Dat	ta Hold Time			0		0		ns
t _{CO}	Clock to Out	tput (Note 3)				7		8	ns
tw∟	Clock			LOW	6		8		ns
t _{WH}	Width			HIGH	6		8		ns
				D-type	50		40		MHz
	Maximum	External Feedback	1/(ts + tco)	T-type	47.6		38.4		MHz
f _{MAX}	Frequency		•	D-type	58.8		45.4		MHz
	(Note 1)	Internal Feedback (fcnt)	T-type	55.5		43.4		MHz
				D-type	76.9		58.8		MHz
		No Feedback	1/(ts + t _H)	T-type	71.4		55.5		MHz
tsL	Setup Time	from Input, I/O, or Fe	edback to Gate		13		17		ns
thL	Latch Data H	•			0		0		ns
t _{GO}	Gate to Outp					8		8	ns
t _{GWL}	Gate Width	. ,			6		8		ns
t _{PDL}	Input, I/O, or	r Feedback to Output							
		Input or Output Latc	h			17		22	ns
tsir	-	er Setup Time			2		2		ns
tHIR		er Hold Time			2.5		3		ns
t _{ICO}		er Clock to Combinat	· · · · · · · · · · · · · · · · · · ·			18		23	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Setup	D-type	17		22		ns
				T-type	18		23		ns
twicl	Input Regist			LOW	6		8		ns
twich	Clock Width			HIGH	6		8		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(twicL +	twich)	83.3		62.5		MHz
tsıL	Input Latch	Setup Time			2		2		ns
t _{HIL}	Input Latch I	Hold Time			2.5		3		ns
tigo	Input Latch Gate to Combinatorial Output				20		25	ns	
tigoL	Input Latch Gate to Output Through Transparent Output Latch				22		27	ns	
tsll		from Input, I/O, or Fe Input Latch to Outpu		n	15		19		ns
t _{IGS}	· ·	Gate to Output Latch			18		23		ns



SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter	arameter		5	-20		
Symbol	bol Parameter Description		Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		8		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches				24	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		25		30	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	20		25		ns
tarr	Asynchronous Reset Recovery Time (Note 1)	20		25		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		25		30	ns
t _{APW}	Asynchronous Preset Width (Note 1)	20		25		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	20		25		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		15		20	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		15		20	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

Storage Temperature65°C to +150°C
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage –0.5 V to V _{CC} + 0.5 V
DC Output or I/O Pin Voltage0.5 V to V _{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current $(T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$ 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Ambient Temperature (T_A)
Operating in Free Air -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	I_{OH} = -3.2 mA, V_{CC} = Min V_{IN} = V_{IH} or V_{IL}	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
l _{IH}	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μА
I _{IL}	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	V _{OUT} = 5.25 V, V _{CC} = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			10	μА
lozL	Off-State Output Leakage Current LOW	V _{OUT} = 0 V, V _{CC} = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			-100	μА
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.



Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)

				<u> </u>	<u> </u>				
Parameter	Parameter Description Input, I/O, or Feedback to Combinatorial Output			-18 Min		-2		l Init	
Symbol				Min	Max 18	Min	Max 24	Unit	
t _{PD}	(Note 3)					18		24	ns
	Setup Time	from Input, I/O,		D-type	16		20.5		ns
ts	or Feedback	to Clock		T-type	17		22		ns
t _H	Register Da	ta Hold Time		•	0		0		ns
t _{CO}	Clock to Out					8.5		10	ns
tw∟	Clock			LOW	7.5		10		ns
t _{WH}	Width	T	1	HIGH	7.5		10		ns
		External Feedback	1/(t _S + t _{CO})	D-type	40		32		MHz
	Maximum	External Feedback	17(15 + 100)	T-type	38		30.5		MHz
f _{MAX}	Frequency	latamal Essalla selet	• \	D-type	47		36		MHz
	(Note 1)	Internal Feedback ((CNT)	T-type	44		34.5		MHz
				D-type	61.5		47		MHz
		No Feedback	1/(t _S + t _H)	T-type	57		47		MHz
t _{SL}	Setup Time	rom Input, I/O, or Fe	edback to Gate	, , , , , , , , , , , , , , , , , , ,	16		20.5		ns
t _{HL}	Latch Data I	•			0		0		ns
t _{GO}	Gate to Outp	out (Note 3)				10		10	ns
t _{GWL}	Gate Width	LOW			7.5		10		ns
t _{PDL}		r Feedback to Output Input or Output Latcl				20.5		26.5	ns
t _{SIR}	Input Regist	er Setup Time			2.5		2.5		ns
t _{HIR}	Input Regist	er Hold Time			3.5		4		ns
t _{ICO}	Input Regist	er Clock to Combinat	orial Output			22		28	ns
tics	Input Regist	er Clock to Output Re	egister Setup	D-type	20.5		26.5		ns
				T-type	22		28		ns
twicL	Input Regist			LOW	7.5		10		ns
twich	Clock Width			HIGH	7.5		10		ns
f _{MAXIR}		put Register Frequer	ncy 1/(t _{WICL} + t	wich)	66.5		50		MHz
t _{SIL}	Input Latch	•			2.5		2.5		ns
t _{HIL}	Input Latch I				3.5		4		ns
tigo	<u> </u>	Gate to Combinatoria	<u> </u>			24		30	ns
tigol	Output Latch	Input Latch Gate to Output Through Transparent Output Latch				26.5		32.5	ns
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu		1	18		23		ns
t _{IGS}	Input Latch	Gate to Output Latch	Setup		22		28		ns
twigL	Input Latch	Gate Width LOW	_		7.5		10		ns
t _{PDLL}		r Feedback to Output utput Latches	Through Transp	parent		23		29	ns

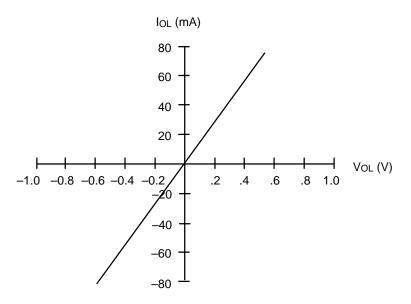
SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2) (continued)

Parameter		-18		-2		
Symbol	Parameter Description		Max	Min	Max	Unit
t _{AR}	Asynchronous Reset to Registered or Latched Output		30		36	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	24		30		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	24		30		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		30		36	ns
t _{APW}	Asynchronous Preset Width (Note 1)	24		30		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	24		30		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		18		24	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		18		24	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

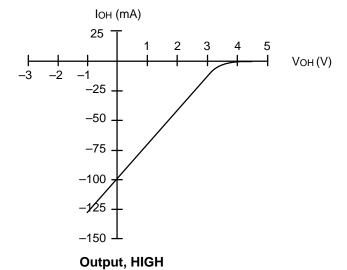
TYPICAL CURRENT VS. VOLTAGE (I-V) CHARACTERISTICS

 $V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C}$

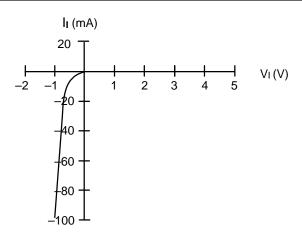


Output, LOW





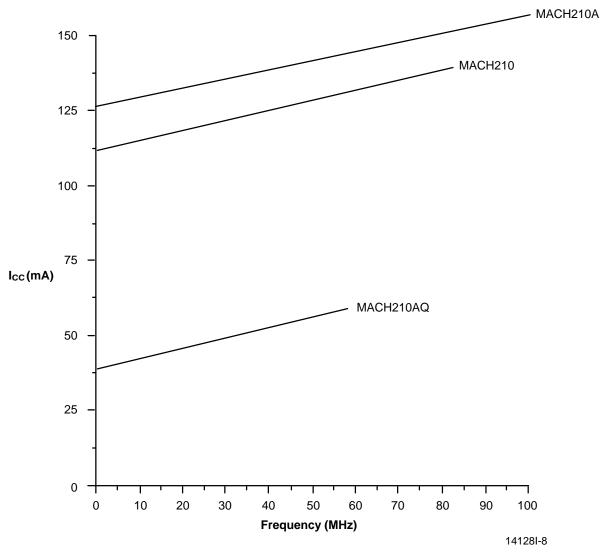
141281-6



141281-7

Input

TYPICAL I_{CC} CHARACTERISTICS $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$



The selected "typical" pattern is a 16-bit up/down counter. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Maximum frequency shown uses internal feedback and a D-type register.



TYPICAL THERMAL CHARACTERISTICS

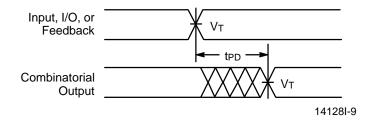
Measured at 25°C ambient. These parameters are not tested.

Parameter	eter			ур	
Symbol	Parameter Description		TQFP	PLCC	Unit
θјс	Thermal impedance, junction to case			15	°C/W
θ_{ja}	Thermal impedance, junction to ambient	41	40	°C/W	
θjma	Thermal impedance, junction to	200 lfpm air	35	36	°C/W
	ambient with air flow	400 Ifpm air	33.7	33	°C/W
			32.6	31	°C/W
		800 Ifpm air	32	29	°C/W

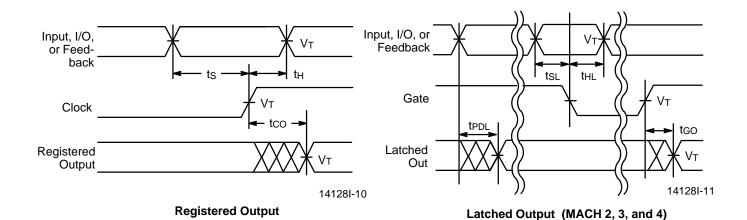
Plastic θ jc Considerations

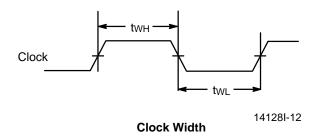
The data listed for plastic θ care for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the θ jc measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore, θ jc tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.

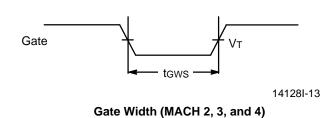
SWITCHING WAVEFORMS

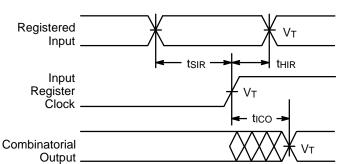


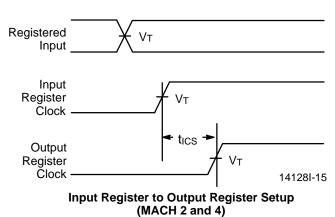
Combinatorial Output











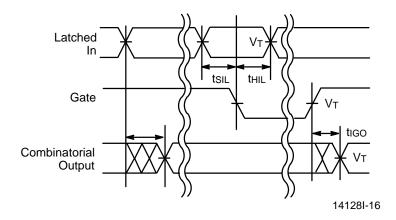
Registered Input (MACH 2 and 4)

Notes:

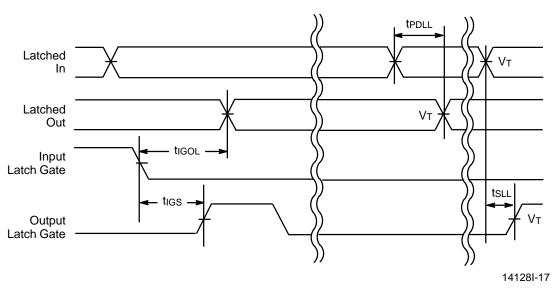
- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

141281-14

SWITCHING WAVEFORMS



Latched Input (MACH 2 and 4)

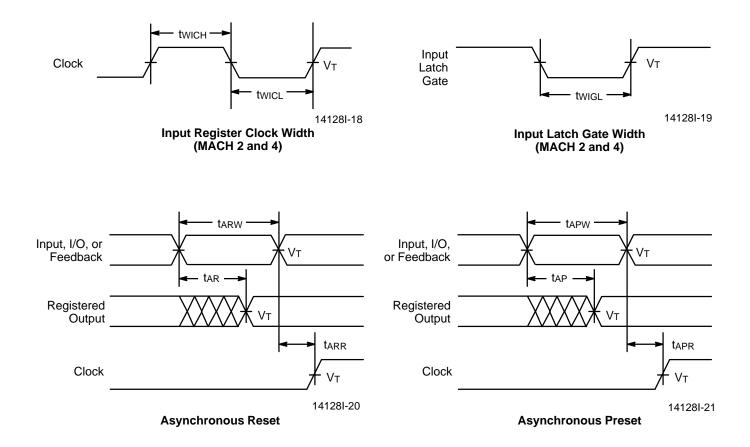


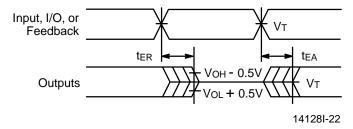
Latched Input and Output (MACH 2, 3, and 4)

Notes:

- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

SWITCHING WAVEFORMS





Output Disable/Enable

Notes:

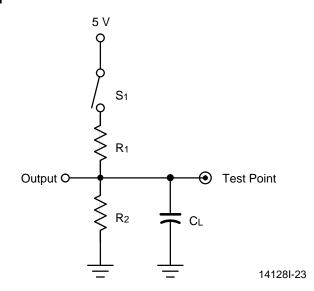
- 1. $V_T = 1.5 V$.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	Must be Steady	Will be Steady
	May Change from H to L	Will be Changing from H to L
	May Change from L to H	Will be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
	Does Not Apply	Center Line is High- Impedance "Off" State

KS000010-PAL

SWITCHING TEST CIRCUIT



			Commercial		Measured
Specification	S ₁	C∟	R ₁	R ₂	Output Value
tpd, tco	Closed				1.5 V
t _{EA}	$Z \rightarrow H$: Open $Z \rightarrow L$: Closed	35 pF	300 Ω	390 Ω	1.5 V
ter	$H \rightarrow Z$: Open $L \rightarrow Z$: Closed	5 pF			$H \rightarrow Z: V_{OH} - 0.5 V$ $L \rightarrow Z: V_{OL} + 0.5 V$

^{*}Switching several outputs simultaneously should be avoided for accurate measurement.

fMAX PARAMETERS

The parameter f_{MAX} is the maximum clock rate at which the device is guaranteed to operate. Because the flexibility inherent in programmable logic devices offers a choice of clocked flip-flop designs, f_{MAX} is specified for three types of synchronous designs.

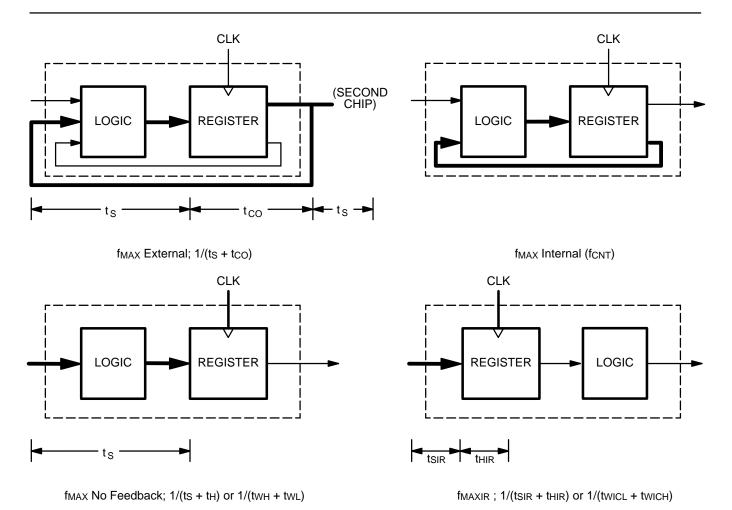
The first type of design is a state machine with feedback signals sent off-chip. This external feedback could go back to the device inputs, or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals ($t_S + t_{CO}$). The reciprocal, f_{MAX} , is the maximum frequency with external feedback or in conjunction with an equivalent speed device. This f_{MAX} is designated " f_{MAX} external."

The second type of design is a single-chip state machine with internal feedback only. In this case, flip-flop inputs are defined by the device inputs and flip-flop outputs. Under these conditions, the period is limited by the internal delay from the flip-flop outputs through the internal feedback and logic to the flip-flop inputs. This f_{MAX} is designated " f_{MAX} internal". A simple internal counter is a good example of this type of design; therefore, this parameter is sometimes called " f_{CNT} ."

The third type of design is a simple data path application. In this case, input data is presented to the flip-flop and clocked through; no feedback is employed. Under these conditions, the period is limited by the sum of the data setup time and the data hold time ($t_S + t_H$). However, a lower limit for the period of each f_{MAX} type is the minimum clock period ($t_{WH} + t_{WL}$). Usually, this minimum clock period determines the period for the third f_{MAX} , designated " f_{MAX} no feedback."

For devices with input registers, one additional f_{MAX} parameter is specified: f_{MAXIR} . Because this involves no feedback, it is calculated the same way as f_{MAX} no feedback. The minimum period will be limited either by the sum of the setup and hold times $(t_{SIR} + t_{HIR})$ or the sum of the clock widths $(t_{WICL} + t_{WICH})$. The clock widths are normally the limiting parameters, so that f_{MAXIR} is specified as $1/(t_{WICL} + t_{WICH})$. Note that if both input and output registers are use in the same path, the overall frequency will be limited by t_{ICS} .

All frequencies except f_{MAX} internal are calculated from other measured AC parameters. f_{MAX} internal is measured directly.



141281-24



ENDURANCE CHARACTERISTICS

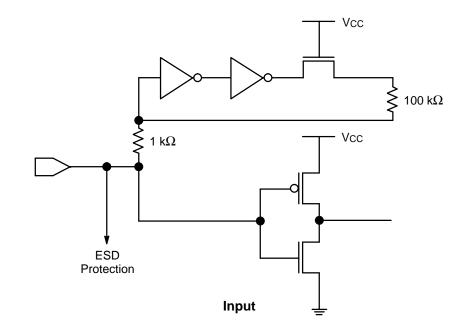
The MACH families are manufactured using AMD's advanced Electrically Erasable process. This technology uses an EE cell to replace the fuse link used in

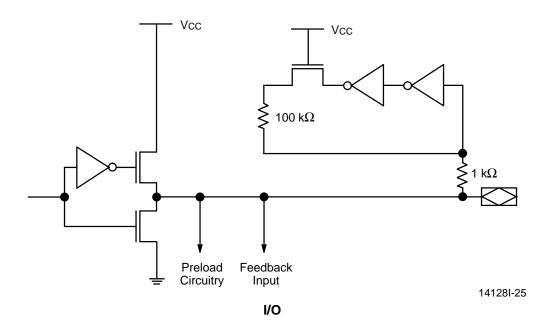
bipolar parts. As a result, the device can be erased and reprogrammed, a feature which allows 100% testing at the factory.

Endurance Characteristics

Parameter Symbol	Parameter Description	Min	Units	Test Conditions
		10	Years	Max Storage Temperature
t _{DR}	Min Pattern Data Retention Time	20	Years	Max Operating Temperature
N	Max Reprogramming Cycles	100	Cycles	Normal Programming Conditions

INPUT/OUTPUT EQUIVALENT SCHEMATICS







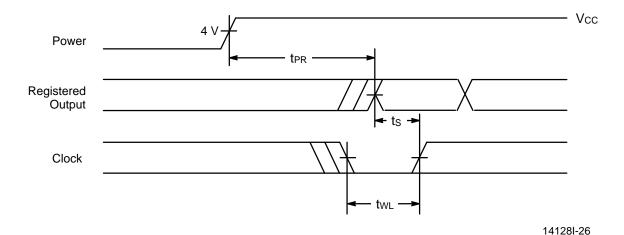
POWER-UP RESET

The MACH devices have been designed with the capability to reset during system power-up. Following power-up, all flip-flops will be reset to LOW. The output state will depend on the logic polarity. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and the

wide range of ways V_{CC} can rise to its steady state, two conditions are required to insure a valid power-up reset. These conditions are:

- 1. The Vcc rise must be monotonic.
- 2. Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Descriptions Max		Unit	
t _{PR}	Power-Up Reset Time	10	10 μs	
ts	Input or Feedback Setup Time	See	See Switching	
t _{WL}	Clock Width LOW	Characteris	Characteristics	



Power-Up Reset Waveform

USING PRELOAD AND OBSERVABILITY

In order to be testable, a circuit must be both controllable and observable. To achieve this, the MACH devices incorporate register preload and observability.

In preload mode, each flip-flop in the MACH device can be loaded from the I/O pins, in order to perform functional testing of complex state machines. Register preload makes it possible to run a series of tests from a known starting state, or to load illegal states and test for proper recovery. This ability to control the MACH device's internal state can shorten test sequences, since it is easier to reach the state of interest.

The observability function makes it possible to see the internal state of the buried registers during test by overriding each register's output enable and activating the output buffer. The values stored in output and buried registers can then be observed on the I/O pins. Without this feature, a thorough functional test would be impossible for any designs with buried registers.

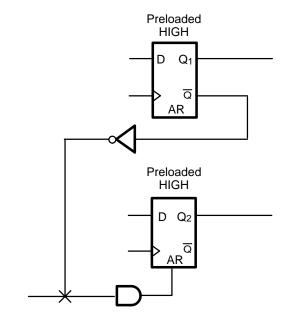
While the implementation of the testability features is fairly straightforward, care must be taken in certain instances to insure valid testing.

One case involves asynchronous reset and preset. If the MACH registers drive asynchronous reset or preset lines and are preloaded in such a way that reset or preset are asserted, the reset or preset may remove the preloaded data. This is illustrated in Figure 2. Care should be taken when planning functional tests, so that states that will cause unexpected resets and presets are not preloaded.

Another case to be aware of arises in testing combinatorial logic. When an output is configured as combinatorial, the observability feature forces the output into registered mode. When this happens, all product terms are forced to zero, which eliminates all combinatorial data. For a straight combinatorial output, the correct value will be restored after the preload or observe function, and there will be no problem. If the function implements a combinatorial latch, however, it relies on feedback to hold the correct value, as shown in Figure 3. As this value may change during the preload or observe operation, you cannot count on the data being correct after the operation. To insure valid testing in these cases, outputs that are combinatorial latches should not be tested immediately following a preload or observe sequence, but should first be restored to a known state.

All MACH 2 devices support both preload and observability.

Contact individual programming vendors in order to verify programmer support.



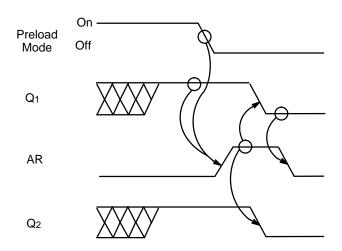


Figure 2. Preload/Reset Conflict

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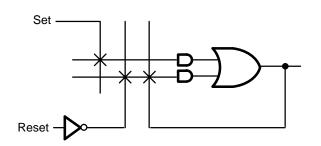


Figure 3. Combinatorial Latch

14128I-28



DEVELOPMENT SYSTEMS (subject to change)

For more information on the products listed below, please consult the AMD FusionPLD Catalog.

MANUFACTURER	SOFTWARE DEVELOPMENT SYSTEMS
Advanced Micro Devices, Inc. P.O. Box 3453, MS 1028 Sunnyvale, CA 94088-3543 (800) 222-9323 or (408) 732-2400	MACHXL [®] Software Ver. 2.0
Advanced Micro Devices, Inc. P.O. Box 3453, MS 1028 Sunnyvale, CA 94088-3543 (800) 222-9323 or (408) 732-2400	Design Center/AMD Software
Advanced Micro Devices, Inc. P.O. Box 3453, MS 1028 Sunnyvale, CA 94088-3543 (800) 222-9323 or (408) 732-2400	AMD-ABEL Software Data I/O MACH Fitters
Advanced Micro Devices, Inc. P.O. Box 3453, MS 1028 Sunnyvale, CA 94088-3543 (800) 222-9323 or (408) 732-2400	PROdeveloper/AMD Software PROsynthesis/AMD Software
Cadence Design Systems 555 River Oaks Pkwy San Jose, CA 95134 (408) 943-1234	ComposerPIC [™] Designer (Requires MACH Fitter) Verilog, LeapFrog, RapidSim Simulators (Models also available from Logic Modeling) Ver. 3.3
Capilano Computing 960 Quayside Dr., Suite 406 New Westminster, B.C. Canada V3M 6G2 (800) 444-9064 or (604) 552-6200	MacABEL™ Software (Requires SmartPart MACH Fitter)
CINA, Inc. P.O. Box 4872 Mountain View, CA 94040 (415) 940-1723	SmartCAT Circuit Analyzer
Data I/O Corporation 10525 Willows Road N.E. P.O. Box 97046 Redmond, WA 98073-9746 (800) 332-8246 or (206) 881-6444	ABEL™-5 Software (Requires MACH Fitter) Synario™ Software
iNt GmbH Busenstrasse 6 D-8033 Martinsried, Munich, Germany (89) 857-6667	PLDSim 90
ISDATA GmbH Daimlerstr. 51 D7500 Karlsruhe 21 Germany Germany: 0721/75 10 87 U.S.: (510) 531-8553	LOG/iC™ Software (Requires MACH Fitter)
Logic Modeling 19500 NW Gibbs Dr. P.O. Box 310 Beaverton, OR 97075 (503) 690-6900	SmartModel [®] Library
Logical Devices, Inc. 692 S. Military Trail Deerfield Beach, FL 33442 (800) 331-7766 or (305) 428-6868	CUPL™ Software

DEVELOPMENT SYSTEMS (subject to change) (continued)

MANUFACTURER	SOFTWARE DEVELOPMENT SYSTEMS	
Mentor Graphics Corp. 8005 S.W. Boeckman Rd. Wilsonville, OR 97070-7777 (800) 547-3000 or (503) 685-7000	PLDSynthesis™ (Requires MACH Fitter) QuickSim Simulator (Models also available from Logic Modeling)	
MicroSim Corp. 20 Fairbanks Irvine, CA 92718 (714) 770-3022	Design Center Software (Requires MACH Fitter)	
MINC Incorporated 6755 Earl Drive, Suite 200 Colorado Springs, CO 80918 (800) 755-FPGA or (719) 590-1155	PLDesigner™-XL Software (Requires MACH Fitter)	
OrCAD 3175 N.W. Aloclek Dr. Hillsboro, OR 97124 (503) 690-9881	Programmable Logic Design Tools 386+ Schematic Design Tool 386+ Digital Simulation Tools	
SUSIE-CAD 10000 Nevada Highway, Suite 201 Boulder City, NV 89005 (702) 293-2271	SUSIE™Simulator	
Teradyne EDA 321 Harrison Ave. Boston, MA 02118 (800) 777-2432 or (617) 422-2793	MultiSIM Interactive Simulator LASAR	
Viewlogic Systems, Inc. 293 Boston Post Road West Marlboro, MA 01752 (800) 442-4660 or (508) 480-0881	ViewPLD or PROPLD (Requires PROSim Simulator MACH Fitter) ViewSim Simulator (Models for ViewSim also available from Logic Modeling)	
MANUFACTURER	TEST GENERATION SYSTEM	
Acugen Software, Inc. 427-3 Amherst St., Suite 391 Nashua, NH 03063 (603) 891-1995	ATGEN™ Test Generation Software	
iNt GmbH Busenstrasse 6 D-8033 Martinsried, Munich, Germany (87) 857-6667	PLDCheck 90	

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For more information on the products listed below, please consult the AMD FusionPLD Catalog.

MANUFACTURER	PROC	GRAMMER CONFIGURATI	ON
Advin Systems, Inc. 1050-L East Duane Ave. Sunnyvale, CA 94086 (408) 243-7000		Pilot U84	
BP Microsystems 100 N. Post Oak Rd. Houston, TX 77055-7237 (800) 225-2102 or (713) 688-4600		BP1200	
Data I/O Corporation 10525 Willows Road N.E. P.O. Box 97046 Redmond, WA 98073-9746 (800) 332-8246 or (206) 881-6444	UniSite™	Model 3900	AutoSite
Logical Devices Inc./Digelec 692 S. Military Trail Deerfield Beach, FL 33442 (800) 331-7766 or (305) 428-6868		ALLPRO™–88	
SMS North America, Inc. 16522 NE 135th Place Redmond, WA 98052 (800) 722-4122 or SMS Im Grund 15 D-7988 Vangen Im Allgau, Germany 07522-5018		Sprint/Expert	
Stag Microsystems Inc. 1600 Wyatt Dr. Suite 3 Santa Clara, CA 95054 (408) 988-1118 or Stag House Martinfield, Welwyn Garden City Herfordshire UK AL7 1JT 707-332148		Stag Quazar	
System General 510 S. Park Victoria Dr. Milpitas, CA 95035 (408) 263-6667 or 3F, No. 1, Alley 8, Lane 45 Bao Shing Rd., Shin Diau Taipei, Taiwan 2-917-3005		Turpro-1	

APPROVED ON-BOARD PROGRAMMERS

MANUFACTURER	PROGRAMMER CONFIGURATION
Corelis, Inc. 12607 Hidden Creek Way, Suite H Cerritos, California 70703 (310) 926-6727	JTAG PROG
Advanced Micro Devices P.O. Box 3453, MS-1028 Sunnyvale, CA 94088-3453 (800) 222-9323	MACHpro



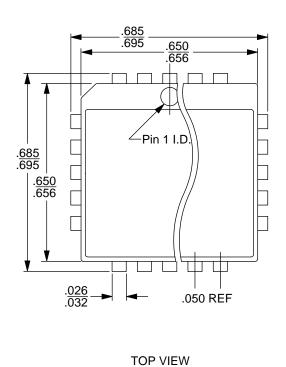
PROGRAMMER SOCKET ADAPTERS (subject to change)

MANUFACTURER	PART NUMBER
EDI Corporation P.O. Box 366 Patterson, CA 95363 (209) 892-3270	Contact Manufacturer
Emulation Technology 2344 Walsh Ave., Bldg. F Santa Clara, CA 95051 (408) 982-0660	Contact Manufacturer
Logical Systems Corp. P.O. Box 6184 Syracuse, NY 13217-6184 (315) 478-0722	Contact Manufacturer
Procon Technologies, Inc. 1333 Lawrence Expwy, Suite 207 Santa Clara, CA 95051 (408) 246-4456	Contact Manufacturer

PHYSICAL DIMENSIONS*

PL 044

44-Pin Plastic Leaded Chip Carrier (measured in inches)



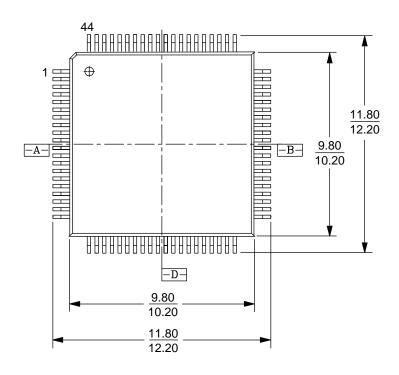
.<u>062</u> .083 .<u>042</u> .056 .500 .590 REF .630 .<u>009</u> .015 .165 .180 SEATING PLANE SIDE VIEW

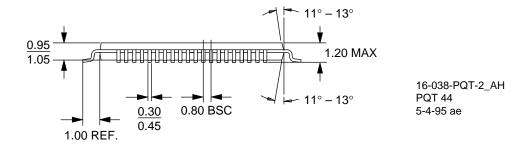
16-038-SQ PL 044 DA78 6-28-94 ae

PHYSICAL DIMENSIONS*

PQT044

44-Pin Thin Quad Flat Pack (measured in millimeters)





*For reference only. BSC is an ANSI standard for Basic Space Centering.

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